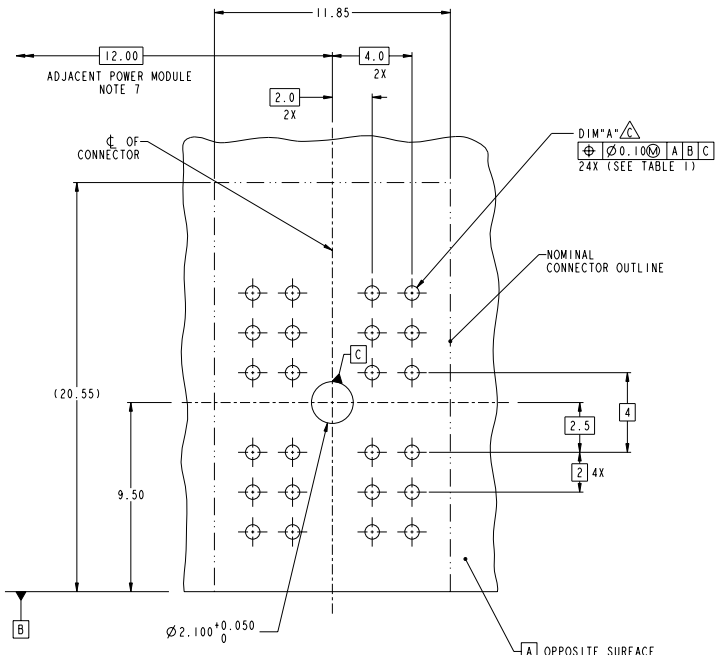


www.fciconnect.com		surface	tolerance std	projection	MM
		ASME Y14.5	ASME Y14.5		Scale
		TOLERANCES UNLESS OTHERWISE SPECIFIED			A2
Dr	T. HOUTZ	2005-03-29	ANGULAR	0.X	M
Eng	ANDREW TONG	2010-05-11	LINEAR	0.XX	M
Chr	C.H. TAN	2010-05-11	0"	0.XXX	M
Appr	JOEY NG	2010-05-11	Product family	2mm High Power	Spec ref
R/A RECEPTACLE POWER ASSEMBLY (2 x 2)		10052620		Rev.	C
catalog no		CUSTOMER		sheet 1 of 2	

PDM: Rev:C STATUS:Released Printed: Dec 01, 2010

TOP LAYER DESCRIPTION	TABLE I PLATED THROUGH-HOLE REQUIREMENTS							
	DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	NICKEL THICKNESS	GOLD THICKNESS	TIN THICKNESS	SILVER THICKNESS	FINISHED HOLE DIAMETER (DIM'A*)
TIN-LEAD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	0.005 - 0.015	--	--	--	--	0.65 - 0.80
IMMERSTON TIN	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	0.9 - 1.5um	--	0.70 - 0.80
IMMERSTON SILVER	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	--	0.15 - 0.65um	0.70 - 0.80
COPPER (SEE NOTE 11)	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	--	--	0.70 - 0.80
GOLD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	0.003 - 0.007	FLASH UP TO 0.0002	--	--	0.69 - 0.80

- NOTES:
- CONNECTOR MATERIALS:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC, BLACK
UL 94V-0 COMPLIANT
CONTACT: HIGH PERFORMANCE COPPER ALLOY
 - a) CONTACT PLATING (LEAD FREE):
PRESS-FIT TAIL: 0.5um MIN MATTE TIN OVER NICKEL.
SEPARABLE INTERFACE: 0.76um MIN GOLD OVER NICKEL.
b) CONTACT PLATING (LEADED):
PRESS-FIT TAIL: 0.5um MIN TIN-LEAD OVER NICKEL.
SEPARABLE INTERFACE: 0.76um MIN GOLD OVER NICKEL.
 - PRODUCT SPECIFICATION: GS-12-220
 - APPLICATION SPECIFICATION: GS-20-023
 - PRODUCT MARKING (PRODUCT NUMBER & DATE CODE) ON HOUSING IN AREA SHOWN.
 - MINIMUM NOMINAL PCB THICKNESS: 1.6mm
 - REFER TO CUSTOMER DRAWING 10035911 FOR INFORMATION REGARDING PCB LAYOUT OF POWER AND GUIDE MODULES RELATIVE TO SIGNAL MODULES.
 - PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN FCI SPECIFICATION GS-22-008.
 - PACKAGING MEETS FCI SPECIFICATION GS-14-920.
 - HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 60 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR PHASE REFLOW OVEN.
 - COPPER PLATING THICKNESS IN CENTER OF VIA-HOLE CAN BE NO MORE THAN 0.003 LESS THAN OTHER AREAS.



RECOMMENDED PCB LAYOUT
COMPONENT SIDE
NOTE 6
SCALE 4:1

FCI	R/A RECEPTACLE POWER	REV	10052620	Rev.
	ASSEMBLY (2 x 2)			
catalog no				

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